Specification of Thermoelectric Module

TES1-07120

Description

The 71 couples, 18 mm × 18 mm size porch type module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

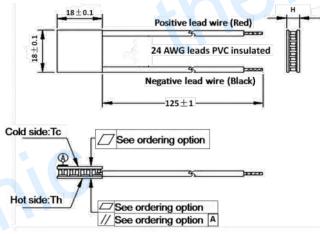
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	9.0	9.8	Voltage applied to the module at DT _{max}	
I _{max} (amps)	2.2	2.2	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	12.3	13.2	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (ohms)	3.1	3.3	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Ordering Option

Thickness	Flatness/	Lead wire length(mm)
H (mm)	Parallelism (mm)	Standard/Optional length
$0:3.4 \pm 0.1$	0:0.05/0.05	125±1/Specify
1:3.4±0.03	1:0.02 /0.02	125±1/Specify
	H (mm) $0:3.4 \pm 0.1$	H (mm) Parallelism (mm) 0:3.4 ± 0.1 0:0.05/0.05

Eg. TF01: Thickness 3.4 ± 0.1 (mm) and Flatness 0.02 / 0.02 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

B. Sealant:

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

nics: D. Ceramics Surface Options:

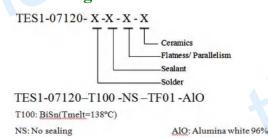
1. Alumina (Al $_2$ O $_3$, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

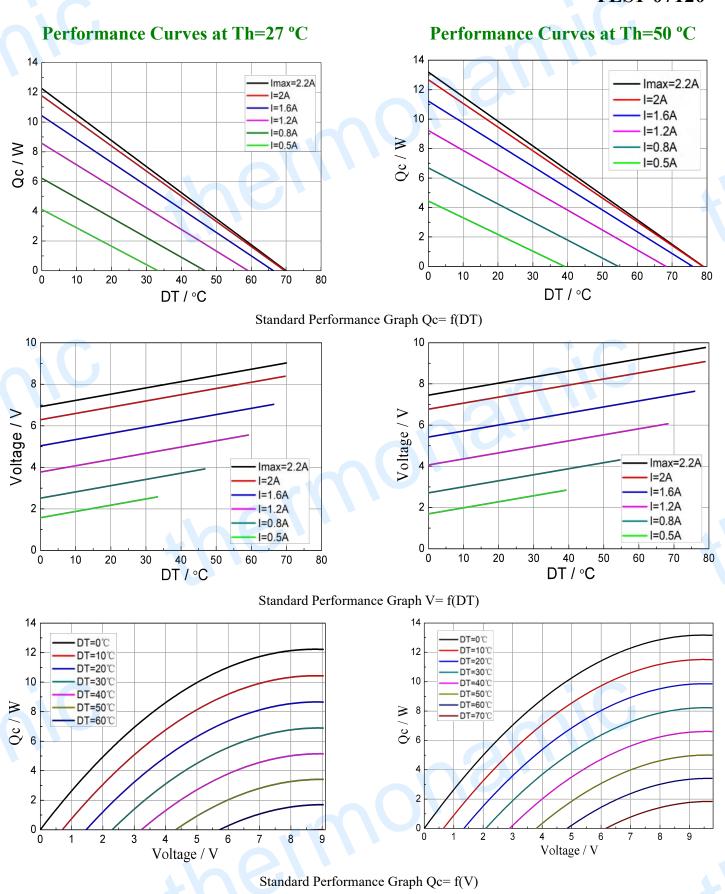
2. Metalized

Naming for the Module



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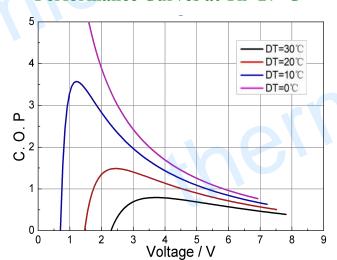
TES1-07120



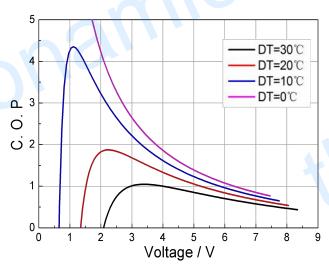
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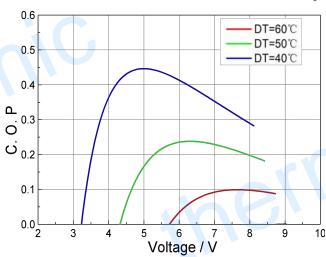
Performance Curves at Th=27 °C

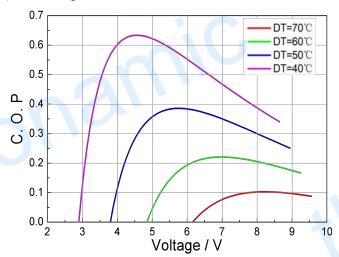


Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.